

## N-Ch 80V Fast Switching MOSFETs

### Features:

- Advanced Trench MOS Technology
- LOW  $R_{DS(ON)}$
- 100% EAS Guaranteed
- Green Device Available

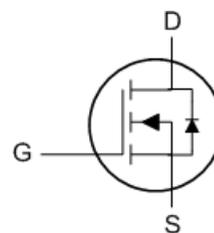
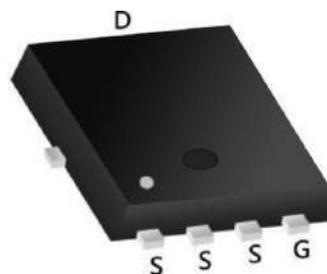
### Applications:

- Power Tools.
- UPS
- Synchronous Rectifier in SMPS.

### Product Summary

BVDSS	RDSON	ID
80V	5mΩ	98A

### PRPAK5X6 Pin Configuration



### Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	80	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D@T_C=25^\circ\text{C}$	Continuous Drain Current, $V_{GS} @ 10V^1$	98	A
$I_D@T_C=100^\circ\text{C}$	Continuous Drain Current, $V_{GS} @ 10V^1$	62	A
$I_D@T_A=25^\circ\text{C}$	Continuous Drain Current, $V_{GS} @ 10V^1$	16	A
$I_D@T_A=70^\circ\text{C}$	Continuous Drain Current, $V_{GS} @ 10V^1$	13	A
$I_{DM}$	Pulsed Drain Current <sup>2</sup>	250	A
EAS	Single Pulse Avalanche Energy <sup>3</sup>	218	mJ
$I_{AS}$	Avalanche Current	66	A
$P_D@T_C=25^\circ\text{C}$	Total Power Dissipation <sup>4</sup>	83	W
$P_D@T_A=25^\circ\text{C}$	Total Power Dissipation <sup>4</sup>	2.3	W
$T_{STG}$	Storage Temperature Range	-55 to 150	$^\circ\text{C}$
$T_J$	Operating Junction Temperature Range	-55 to 150	$^\circ\text{C}$

### Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-Ambient <sup>1</sup>	---	55	$^\circ\text{C/W}$
$R_{\theta JC}$	Thermal Resistance Junction-Case <sup>1</sup>	---	1.5	$^\circ\text{C/W}$

**Electrical Characteristics (T<sub>J</sub>=25 °C, unless otherwise noted)**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =250uA	80	---	---	V
R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =10V, I <sub>D</sub> =20A	---	3.6	5	mΩ
		V <sub>GS</sub> =4.5V, I <sub>D</sub> =20A	---	5.1	7	
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =250uA	1.2	1.7	2.3	V
I <sub>DSS</sub>	Drain-Source Leakage Current	V <sub>DS</sub> =64V, V <sub>GS</sub> =0V, T <sub>J</sub> =25°C	---	---	1	uA
		V <sub>DS</sub> =64V, V <sub>GS</sub> =0V, T <sub>J</sub> =55°C	---	---	5	
I <sub>GSS</sub>	Gate-Source Leakage Current	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V	---	---	±100	nA
R <sub>g</sub>	Gate Resistance	V <sub>DS</sub> =0V, V <sub>GS</sub> =0V, f=1MHz	---	1.4	---	Ω
Q <sub>g</sub>	Total Gate Charge	V <sub>DS</sub> =64V, V <sub>GS</sub> =10V, I <sub>D</sub> =20A	---	52.7	---	nC
Q <sub>gs</sub>	Gate-Source Charge		---	7.8	---	
Q <sub>gd</sub>	Gate-Drain Charge		---	12.5	---	
T <sub>d(on)</sub>	Turn-On Delay Time	V <sub>DD</sub> =64V, V <sub>GS</sub> =10V, R <sub>G</sub> =3Ω, I <sub>D</sub> =20A	---	10	---	ns
T <sub>r</sub>	Rise Time		---	37	---	
T <sub>d(off)</sub>	Turn-Off Delay Time		---	42	---	
T <sub>f</sub>	Fall Time		---	68	---	
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =40V, V <sub>GS</sub> =0V, f=1MHz	---	2792	---	pF
C <sub>oss</sub>	Output Capacitance		---	639	---	
C <sub>rss</sub>	Reverse Transfer Capacitance		---	9.5	---	

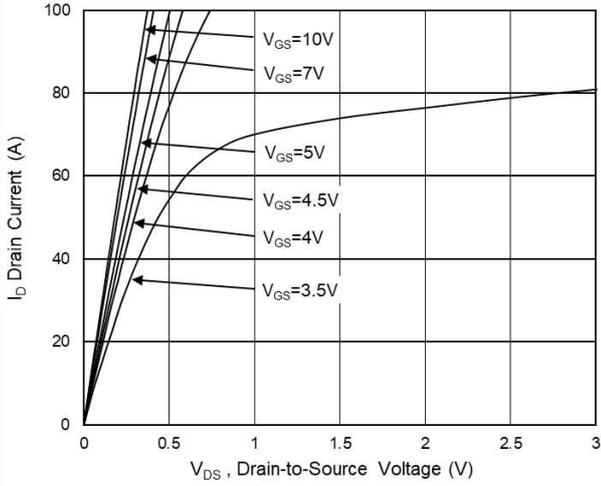
**Diode Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I <sub>S</sub>	Continuous Source Current <sup>1,5</sup>	V <sub>G</sub> =V <sub>D</sub> =0V, Force Current	---	---	98	A
V <sub>SD</sub>	Diode Forward Voltage <sup>2</sup>	V <sub>GS</sub> =0V, I <sub>S</sub> =1A, T <sub>J</sub> =25°C	---	---	1.2	V
t <sub>rr</sub>	Reverse Recovery Time	I <sub>F</sub> =20A, di/dt=100A/μs,	---	23	---	nS
Q <sub>rr</sub>	Reverse Recovery Charge	T <sub>J</sub> =25°C	---	22	---	nC

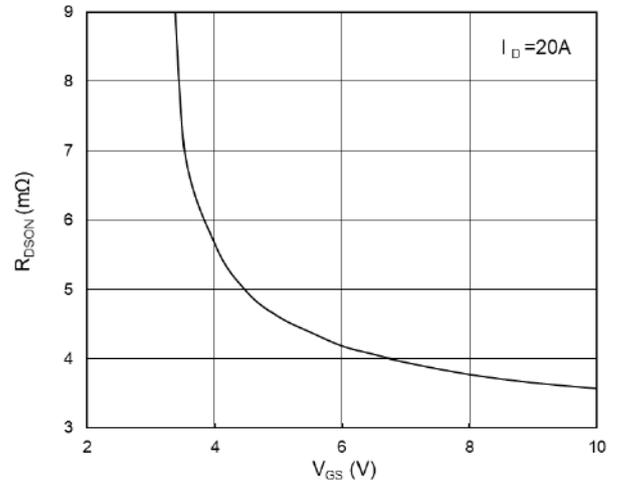
Note :

- 1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%
- 3.The EAS data shows Max. rating . The test condition is V<sub>DD</sub>=25V, V<sub>GS</sub>=10V, L=0.1mH, I<sub>AS</sub>=66A
- 4.The power dissipation is limited by 150°C junction temperature
- 5.The data is theoretically the same as I<sub>D</sub> and I<sub>DM</sub> , in real applications , should be limited by total power dissipation.

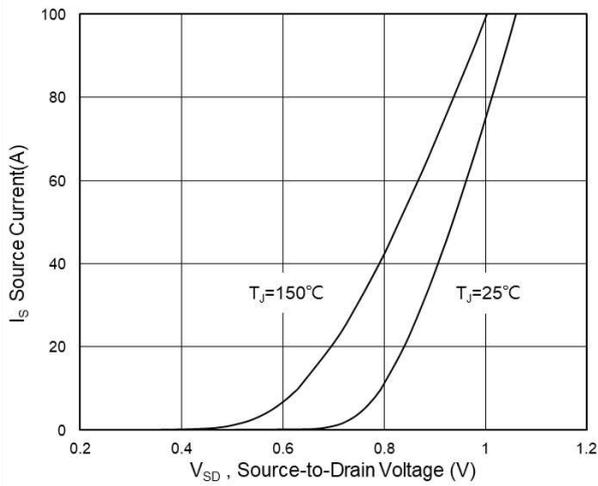
**Typical Characteristics**



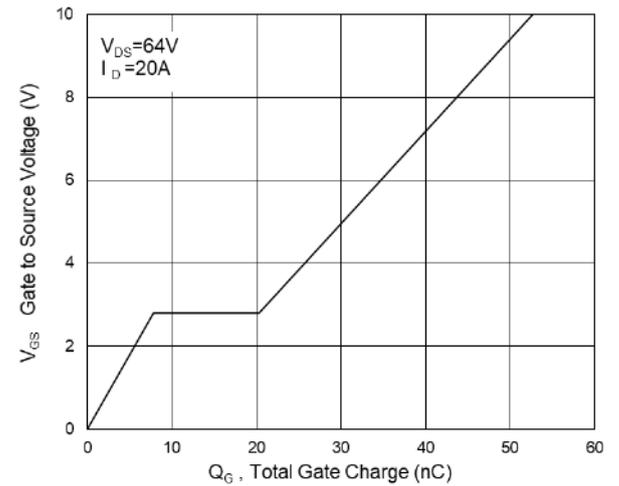
**Fig.1 Typical Output Characteristics**



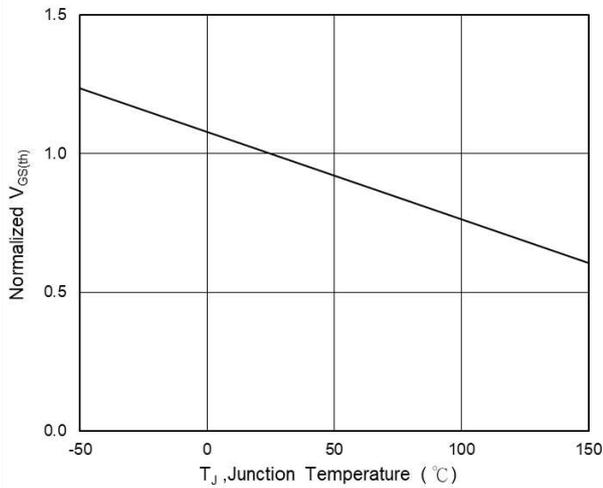
**Fig.2 On-Resistance vs G-S Voltage**



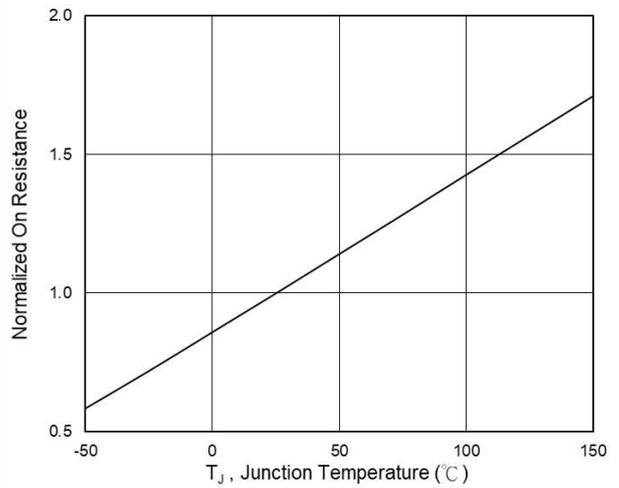
**Fig.3 Source Drain Forward Characteristics**



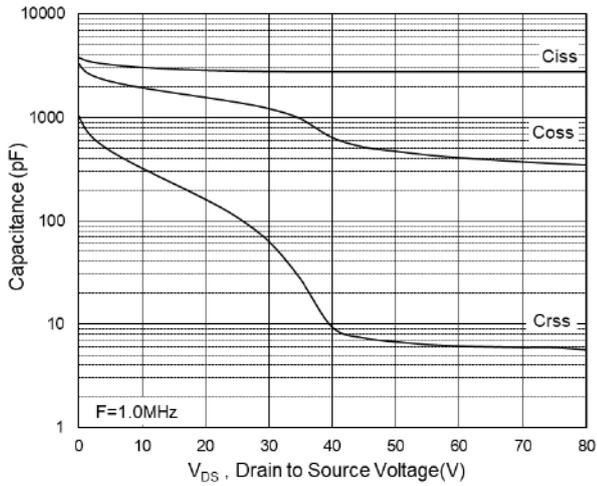
**Fig.4 Gate-Charge Characteristics**



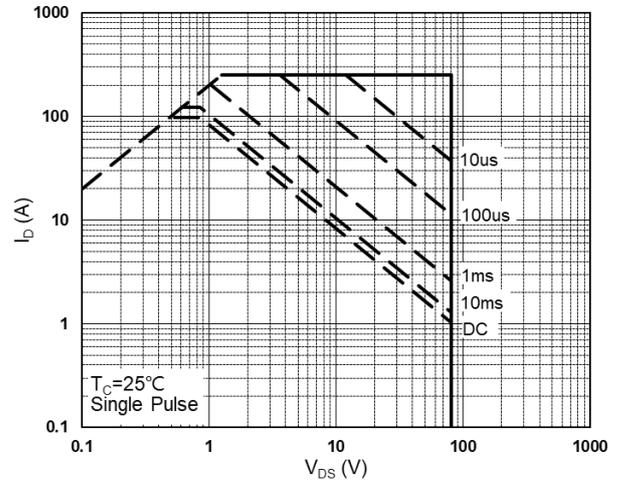
**Fig.5 Normalized  $V_{GS(th)}$  vs  $T_J$**



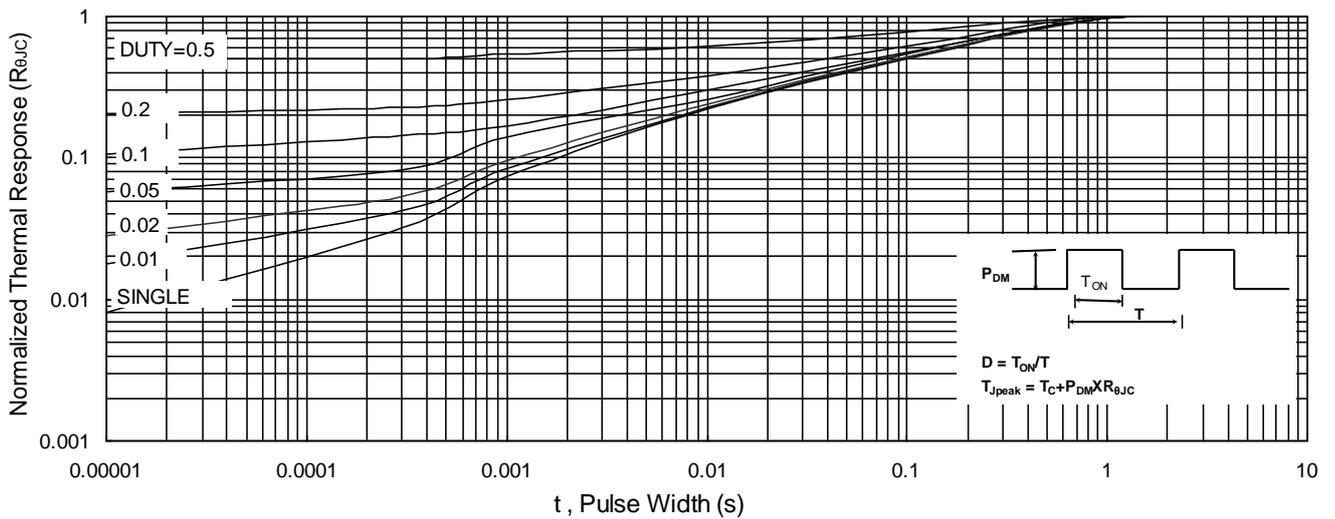
**Fig.6 Normalized  $R_{DS(on)}$  vs  $T_J$**



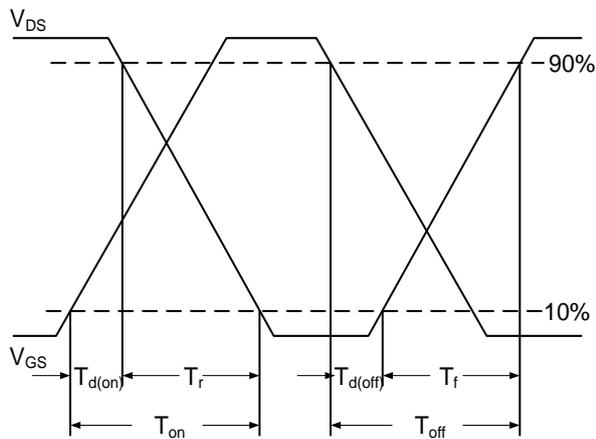
**Fig.7 Capacitance**



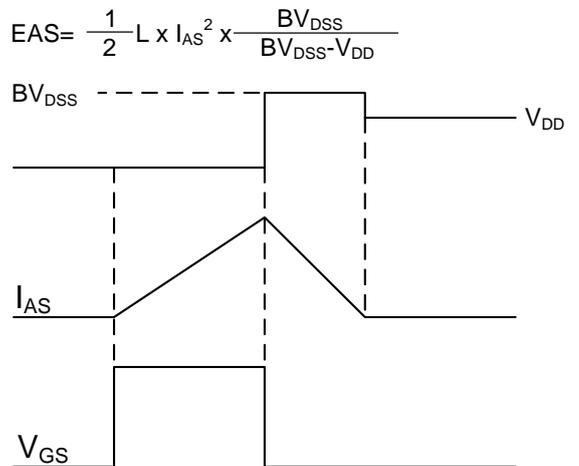
**Fig.8 Safe Operating Area**



**Fig.9 Normalized Maximum Transient Thermal Impedance**



**Fig.10 Switching Time Waveform**



**Fig.11 Unclamped Inductive Waveform**